Serial number: 10/815,420

LISTING OF THE CLAIMS

Claim 1	currently amended
Claim 2	original
Claim 3	original
Claim 4	currently amended
Claim 5	currently amended
Claim 6	currently amended
Claim 7	currently amended
Claim 8	currently amended
Claim 9	original

Serial number: 10/815,420

TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. (currently amended) A multilayer dicing die bonding film ~~for disposition~~ disposed between a semiconductor silicon wafer and a dicing support tape, the dicing die bonding film comprising

(a) Layer-1 adhesive, ~~which comes~~ in contact with the dicing support tape, and

(b) Layer-2 adhesive, ~~which comes~~ in contact with the semiconductor silicon wafer,

in which the adhesion of Layer-2 to the silicon wafer is higher than the adhesion of Layer-1 to the dicing tape by at least 0.1N/cm.

2. (original) The dicing die bonding film of claim 1 in which the Layer-1 adhesive has a characteristic peel strength to the dicing tape in the range of 0.05 to less than 0.5 N/cm, and the Layer-2 adhesive has a characteristic peel strength to the semiconductor silicon wafer in the range of 0.5 to 10 N/cm.

3. (original) The dicing die bonding film of claim 1 in which the Layer-1 adhesive comprises (a) thermoplastic rubber, (b) thermoset resin having a softening point above 60ºC, (c) hardener, (d) accelerator, and (e) filler; and in which the Layer-2 adhesive comprises (a) thermo-plastic rubber, (b) thermoset resin in which at least 20% of the thermoset resin has a softening point below 60ºC, (c) hardener, (d) accelerator, and (e) filler.

4. (currently amended) The dicing die bonding film of claim 3 in which the Layer-1 adhesive comprises (a) 30-85 weight % thermoplastic rubber, (b) 15-70 weight % thermoset resin having a softening point above 60ºC, (c) 0.05-40 weight % hardener, (d) 0.01-10 weight % accelerator, and (e) 1- ~~80~~ 55 weight % filler and the Layer-2 adhesive comprises (a) 30-85 weight % thermoplastic rubber, (b) 15-70 weight % thermoset resin, in which at least 20% of the thermoset resin has a softening point below 60ºC, (c) 0.05-40 weight % hardener, (d) 0.01-10 weight % accelerator, and (e) 1- ~~80~~ 55 weight % filler.

Serial number: 10/815,420

5. (currently amended) The dicing die bonding film of claim ~~4~~ 3 or claim 4 in which the thermoset resin in Layer-1 is a solid epoxy with a softening point of greater than 60ºC and a weight per epoxy equivalent of 100 to 1000.

6. (currently amended) The dicing die bonding film of claim ~~4~~ 3 or claim 4 in which the thermoset resin in Layer-2 is an epoxy having a softening point below 60ºC and a weight per epoxy equivalent of 100 to 1000.

7. (currently amended) The dicing die bonding film of claim ~~4~~ 3 or claim 4 in which the thermoset resin in Layer-2 is a mixture of thermoset resins and at least 20% of the total Layer-2 thermoset resins have a softening point below 60ºC.

8. (currently amended) The dicing die bonding film of claim ~~4~~ 3 or claim 4 in which the thermoplastic rubber is carboxy terminated butadiene-nitrile/epoxy adduct and nitrile butadiene rubber.

9. (original) The dicing die bonding film of claim 8 in which the carboxy terminated butadiene-nitrile/epoxy adduct consists of about 20-80 wt% carboxy terminated butadiene-nitrile and about 20-80 wt% diglycidyl ether bisphenol A : bisphenol A epoxy.

Serial number: 10/815,420

AMENDMENT TO THE SPECIFICATION

Please amend paragraph [0010] of the specification as follows:

[0010] Although any adhesives that meet the above peel strength and lamination criteria can be used, one suitable formulation for both Layer 1 and Layer 2 will contain (a) thermoplastic rubber, (b) thermoset resin, (c) hardener, (d) accelerator, and (e) filler, in which the thermoset resin for Layer 1 will have a softening point greater than 60ºC, and the thermoset resin for Layer 2 will have a softening point below 60ºC. Within this specification, the softening point of a material is defined as its melting point (Tm) or glass transition temperature (Tg). Typical weight percent ranges for this embodiment are 30-85 wt% thermoplastic rubber, 15-70 wt% thermoset resin, 0.05-40 weight % hardener, 0.01-10 weight % accelerator, and 1-~~80~~ 55 weight % filler.